



DZ26330×0L

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Silicon epitaxial planar type

For constant voltage / For surge absorption circuit
DZ27330 in ML2 type package

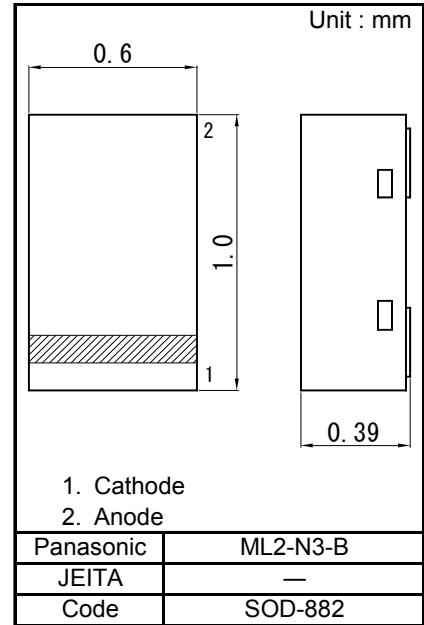
■ Features

- Excellent rising characteristics of zener current IZ
- Low zener operating resistance RZ
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol :HG or HR

■ Packaging

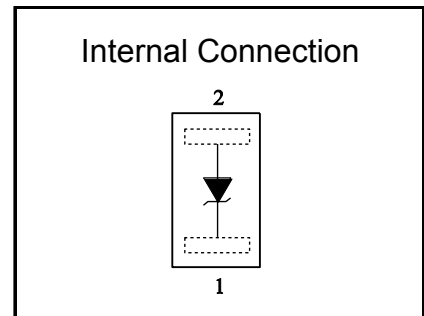
Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	100	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 PT = 100 mW achieved with a printed circuit board.
*2 Test method:IEC61000_4_2
(C = 150 pF , R = 330 Ω , Contact discharge : 10 times)



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 2 mA	31.35		34.65	V
Zener operating resistance	RZ	IZ = 2 mA			200	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 25 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		32.0		mV/°C

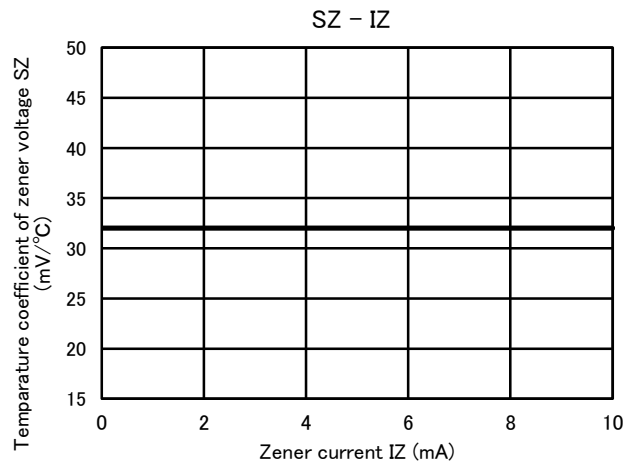
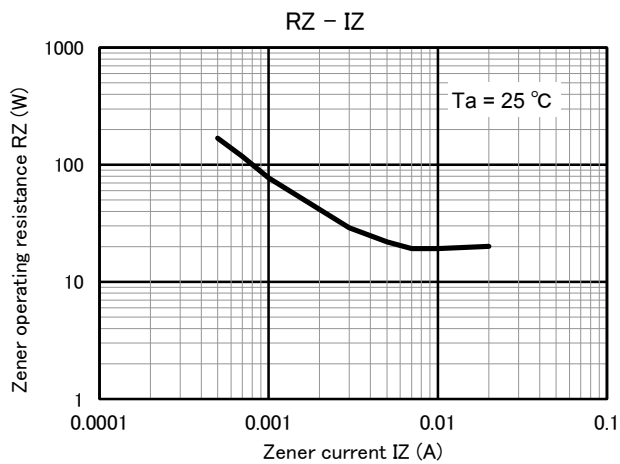
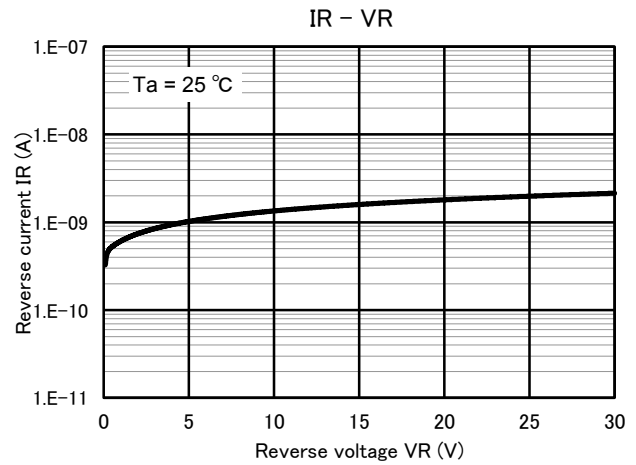
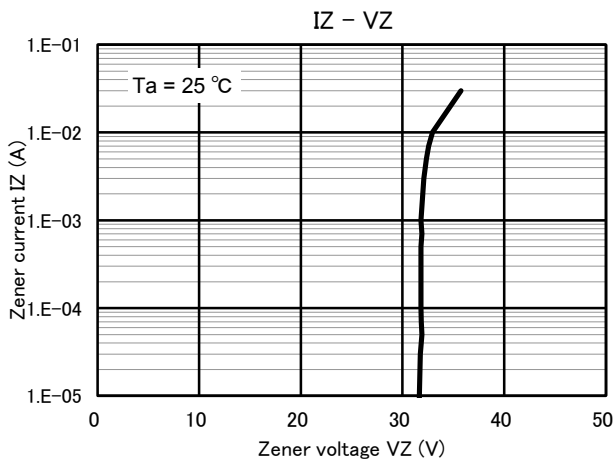
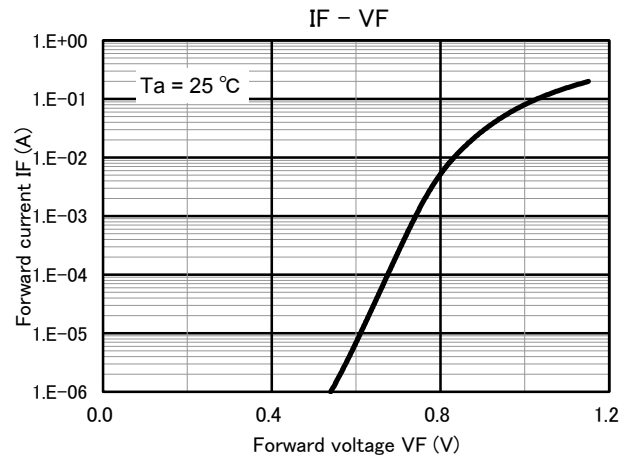
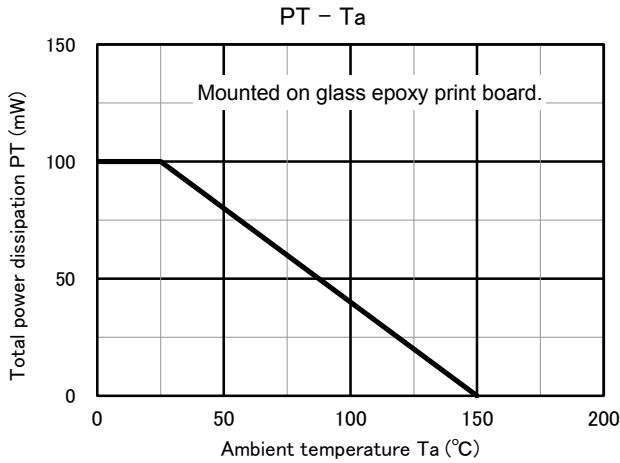
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 5 MHz.
3. *1 The temperature must be controlled 25 °C for VZ mesurement.
VZ value measured at other temperature must be adjusted to VZ (25 °C)
*2 VZ guaranteed 20 ms after current flow.
*3 Tj = 25 °C to 150 °C

Rank classification

Code	M	0
Rank	M	No-rank
VZ	32.20 to 33.80	31.35 to 34.65
Marking symbol	HR	HG

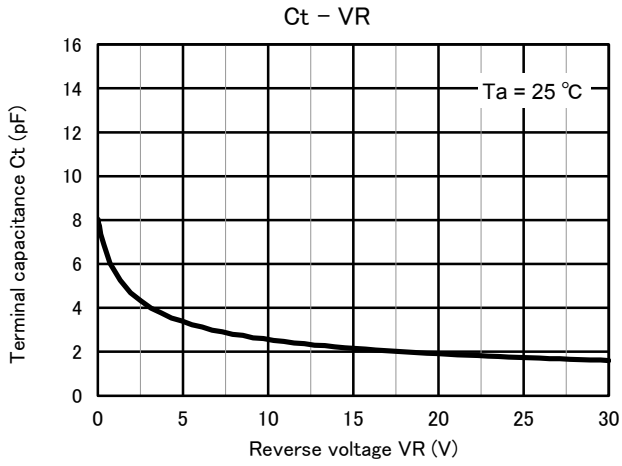


Technical Data (reference)



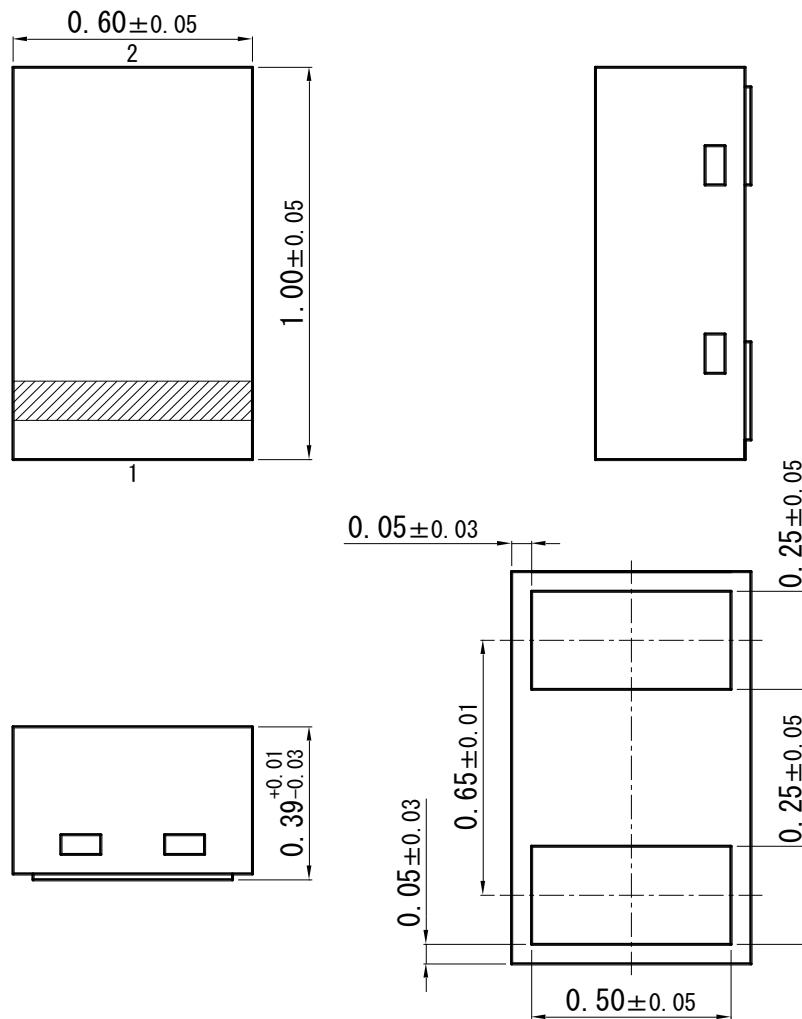


Technical Data (reference)

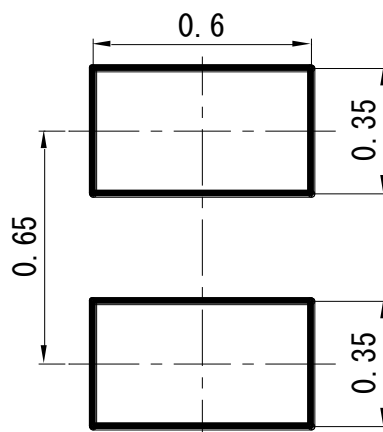


ML2-N3-B

Unit : mm



■ Land Pattern (Reference) (Unit : mm)



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